



Final Product/Process Change Notification
 Document #:FPCN23990X
 Issue Date:06 Jan 2022

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|---|--|---------------------------------|
| Title of Change: | Wire conversion from 2.0 mil Au to 2.0 mil bare Cu wire and change of mold compound impacting Low VCE(sat) BJTs assembled in SOIC-8 package | |
| Proposed First Ship date: | 13 Apr 2022 or earlier if approved by customer | |
| Contact Information: | Contact your local onsemi Sales Office | |
| PCN Samples Contact: | Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. | |
| Additional Reliability Data: | Contact your local onsemi Sales Office or Nhel.Malonzo@onsemi.com | |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com | |
| Marking of Parts/ Traceability of Change: | Customers may receive these parts once FPCN expired. These parts can be identified through date code marking. | |
| Change Category: | Assembly Change | |
| Change Sub-Category(s): | Material Change | |
| Sites Affected: | | |
| onsemi Sites | External Foundry/Subcon Sites | |
| onsemi Carmona, Philippines | None | |
| Description and Purpose: | | |
| Conversion of Copper wire from 2.0 mils Au wire into 2.0 mils Bare Cu wire and mold compound changes from EME G600 to EME G700LS. | | |
| Purpose of the changes for material standardized. | | |
| | Before Change Description | After Change Description |
| Bond Wire | 2.0 mils Au | 2.0 mils Bare Cu |
| Mold Compound | EME G600 | EME G700LS |
| There is no product marking change. | | |



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Reliability Data Summary:

QV DEVICE NAME: NSV40302PDR2G

RMS: O77475

PACKAGE: SOIC 8

| Test | Specification | Condition | Interval | Results |
|------|------------------------------------|--|------------|---------|
| HTRB | JESD22-A108 | Ta=150°C, 100% max rated V | 2016 hrs | 0/240 |
| IOL | MIL-STD-750 (M1037) AEC-Q101 | Ta=+25°C, delta Tj=100°C On/off = 2 min | 30 000 cyc | 0/237 |
| TC | JESD22-A104 | Ta= -55°C to +150°C | 2000 cyc | 0/240 |
| HAST | JESD22-A110 | 130°C, 85% RH, 18.8psig, bias | 192 hrs | 0/240 |
| AC | JESD22-A102 | 121°C, 100% RH, 15 PSIG | 96 hrs | 0/240 |
| PC | J-STD-020 JESD-A113 | MSL 1 @ 260 °C | | 0/957 |
| RSH | JESD22- B106 | Ta = 265C, 10 sec | | 0/30 |
| SD | JSTD002 | Ta = 245C, 5 sec | | 0/45 |
| PD | JESD22 B-100 | Per POD | | 0/30 |

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

| Part Number | Qualification Vehicle |
|---------------|-----------------------|
| NSS40302PDR2G | NSV40302PDR2G |
| NSS40300MDR2G | NSV40302PDR2G |
| NSS40301MDR2G | NSV40302PDR2G |
| NSS40300DDR2G | NSV40302PDR2G |